

**PART INFORMATION**

Mfg Item Number	MC34PF1510A4EPR2
Mfg Item Name	QFN 5x5 40IO P0.4

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-04-02
Response Document ID	00NFK00229D023A1.1
Contact Name	Freescale Semiconductor Inc
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Representative Title	EPP Customer Response
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**DECLARATION**

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	

**MANUFACTURING**

Mfg Item Number	MC34PF1510A4EPR2
Mfg Item Name	QFN 5x5 40IO P0.4
Version	ALL
Weight	0.060000
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Copper Lead Frame	0.0066						g				
Copper Lead Frame		Metals	Chromium, metal	7440-47-3		0.00001786	g	2706	0.2706	297	0.0297
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.00652216	g	888206	98.8206	108702	10.8702
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.00003028	g	4588	0.4588	504	0.0504
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.0000165	g	2500	0.25	275	0.0275
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.0000132	g	2000	0.2	220	0.022
Epoxy Die Attach	0.0008						g				
Epoxy Die Attach		Plastics/polymers	Other Epoxy resins	-		0.00008	g	100000	10	1333	0.1333
Epoxy Die Attach		Glass	Dimethyl silicone polymer with silica	67762-90-7		0.0000243	g	30380	3.038	405	0.0405
Epoxy Die Attach		Polymers	2-Propenenitrile, polymer with 1,3-butadiene, carboxy-terminated, polymers with bisphenol A and epic	68610-41-3		0.0006957	g	869620	86.962	11595	1.1595
Bonding Wire, PdCu	0.0017						g				
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.0016745	g	985000	98.5	27908	2.7908
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.0000017	g	1000	0.1	29	0.0029
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.0000238	g	14000	1.4	396	0.0396
Die Encapsulant, Halogen-free	0.0443						g				
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.001329	g	30000	3	22150	2.215
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.003544	g	80000	8	59066	5.9066
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.039427	g	890000	89	657121	65.7121
Silicon Semiconductor Die	0.0066						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000132	g	20000	2	2200	0.22
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.006468	g	980000	98	107800	10.78

**LINKS**

MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/MC34PF1510A4EPR2\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/MC34PF1510A4EPR2_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/MC34PF1510A4EPR2\\_IPC1752A.xml](http://www.freescale.com/mcdfs/MC34PF1510A4EPR2_IPC1752A.xml)